

Product / Process Change Notification



N° 2018-042-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Implementation of 300 mm wafer diameter and capacity extension for 650V TRENCHSTOP™ 5 bare die products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **6th November 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



N° 2018-042-A

► **Products affected:**

Please refer to attached affected product list 1_cip18042_a

► **Detailed Change Information:**

Subject: Implementation of 300mm wafer diameter

Reason: To ensure continuous deliveries to our customers, the fabrication for above mentioned products requires a capacity extension

Description:	Old	New
Wafer diameter	200mm	200mm and 300mm
Wafer production & test site and lot code	Infineon Technologies Austria AG, Villach, Austria Lot code: VExxxxxx	200mm: Infineon Technologies Austria AG, Villach, Austria Lot code: VExxxxxx and 300mm: Infineon Technologies AG, Dresden, Germany Lot code: ZFxxxxxx
Wafer sorting	Inked. Non-functional chips are indicated by inkdots on chip surface	200mm: Inked. Non-functional chips are indicated by inkdots on chip surface and 300mm: Inkless. Non-functional chips are indicated in electronic wafer map file provided together with every wafer. Reliable 1st die detection is ensured by several alignment marks in the wafer edge area.

Product / Process Change Notification



N° 2018-042-A

**Dimensions of horizontal
frame shipper (L x W x H)**

328mm x 328mm x 112mm

200mm:
328mm x 328mm x 112mm

and

300mm:
434mm x 434mm x 140mm

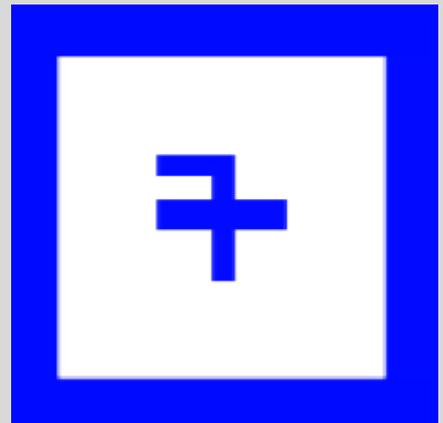
**Alignment marks in wafer
edge area**

No alignment marks

200mm:
No alignment marks

and

300mm:
Dedicated alignment marks



Sales name

Containing „65U8“ (e.g.
IGC16T65U8Q)

200mm:
Containing „65U8“ (e.g.
IGC16T65U8Q)

and

300mm:
Containing „65U12“ (e.g.
IGC16T65U12Q)

► **Product Identification:**

Internal traceability assured via basic type, lot code and development code.

External traceability:

Sales code / Product Barcode Label / Lot code

Product / Process Change Notification



N° 2018-042-A

► **Impact of Change:**

No impact on reliability as proven via product and technology qualification.

Processes are optimized to meet identical product performance according to already applied Infineon specifications.

► **Attachments:**

Affected product list 1_cip18042_a
Qualification report 2_cip18042_a

► **Time Schedule:**

- Final qualification report: 2019-September-09
- First samples available: on request with a lead time of approx. 12 weeks
- Intended start of delivery: 2020-January-15 or earlier on specific customer request

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 2018-042-AImplementation of 300 mm wafer diameter and capacity extension for
650V TRENCHSTOP™ 5 bare die products

Sales name	SP number	OPN	Package
IGC06T65U8F	SP001073496	IGC06T65U8FX1SA1	n.a.
IGC06T65U8F	SP001216100	IGC06T65U8FX7SA1	n.a.
IGC06T65U8Q	SP001073506	IGC06T65U8QX1SA1	n.a.
IGC06T65U8Q	SP001216102	IGC06T65U8QX7SA1	n.a.
IGC08R65U8W	SP001649934	IGC08R65U8WX7SA1	n.a.
IGC08T65U8F	SP001136344	IGC08T65U8FX7SA1	n.a.
IGC08T65U8Q	SP001136346	IGC08T65U8QX7SA1	n.a.
IGC10R65U8W	SP001420766	IGC10R65U8WX7SA1	n.a.
IGC10T65U8F	SP001073498	IGC10T65U8FX1SA1	n.a.
IGC10T65U8F	SP001216104	IGC10T65U8FX7SA1	n.a.
IGC10T65U8Q	SP001073508	IGC10T65U8QX1SA1	n.a.
IGC10T65U8Q	SP001216106	IGC10T65U8QX7SA1	n.a.
IGC10T65U8S	SP001366050	IGC10T65U8SX7SA1	n.a.
IGC10T65U8S	SP001461118	IGC10T65U8SX7SA2	n.a.
IGC13R65U8W	SP001649936	IGC13R65U8WX7SA1	n.a.
IGC13R65U8W2	SP001649938	IGC13R65U8W2X7SA1	n.a.
IGC13T65U8Q	SP001073510	IGC13T65U8QX1SA1	n.a.
IGC13T65U8Q	SP001216110	IGC13T65U8QX7SA1	n.a.
IGC13T65U8S	SP001366052	IGC13T65U8SX7SA1	n.a.
IGC13T65U8S	SP001461120	IGC13T65U8SX7SA2	n.a.
IGC13T65U8V	SP001149256	IGC13T65U8VX7SA1	n.a.
IGC13T65U8V	SP001713444	IGC13T65U8VX7SA2	n.a.
IGC16R65U8W	SP001649942	IGC16R65U8WX7SA1	n.a.
IGC16T65U8Q	SP001073512	IGC16T65U8QX1SA1	n.a.
IGC16T65U8Q	SP001174532	IGC16T65U8QX7SA1	n.a.
IGC16T65U8Q	SP001216114	IGC16T65U8QX7SA2	n.a.
IGC16T65U8S	SP001366054	IGC16T65U8SX7SA1	n.a.
IGC16T65U8S	SP001461154	IGC16T65U8SX7SA2	n.a.
IGC23T65U8Q	SP001315390	IGC23T65U8QX7SA1	n.a.
IGC23T65U8Q	SP001713442	IGC23T65U8QX7SA2	n.a.
IGC23T65U8S	SP001366056	IGC23T65U8SX7SA1	n.a.
IGC23T65U8S	SP001461156	IGC23T65U8SX7SA2	n.a.
IGC30T65U8Q	SP001315392	IGC30T65U8QX7SA1	n.a.
IGC30T65U8V	SP001149254	IGC30T65U8VX7SA1	n.a.
IGC30T65U8V	SP001713438	IGC30T65U8VX7SA2	n.a.